

DECEMBER 7, 1964

5 with a metal thin film, is configured to comprise the steps of:
biasing a conductive material to one surface of the heat
resistant resin film; and applying electrolytic plating to the
heat resistant resin film while using the conductive material
biased to the one surface of the heat resistant resin film as
10 an electrode, so as to form a metal thin film on the heat
resistant resin film.